Electronic Acknowledgement Receipt					
EFS ID:	1066002				
Application Number:	10053963				
Confirmation Number:	5214				
Title of Invention:	Die assembly and method for forming a die on a wafer				
First Named Inventor:	Aron T. Lunde				
Correspondence Address:	Deborah K. Henscheid, Esq.  Snell & Wilmer, L.L.P.  One Arizona Center  400 E. Van Buren  Phoenix AZ 85004-2202  US 6023826070				
Filer:	J. Damon Ashcraft/Julie Eslick				
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Attorney Docket Number:	37829.0400				
Receipt Date:	02-JUN-2006				
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Time Stamp:	18:12:48				
Application Type:	Utility				
International Application Number:					

## Payment information:

Submitted with Payment	no	
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## File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages		
1	Change of Address	378290400COA.pdf	46902	no	1		
Warnings:							
Information:							
		Total Files Size (in bytes): 46902					

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## New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

## National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.